CLAIMS

[Claim 1] A silver powder comprising:

a volume-based cumulative 50 % diameter D_{50} measured by a laser diffraction method of 0.1 μm or more and 1.0 μm or less;

a ratio of D_{50} to BET diameter D_{BET} of 0.8 or more and 1.3 or less; and

a shrinkage ratio at 200 °C in thermomechanical analysis of 1 % or more and 5.0% or less.

[Claim 2] The silver powder according to claim 1, comprising a shrinkage ratio at 150 °C in thermomechanical analysis of 0.6 % or more.

[Claim 3] The silver powder according to claim 1, comprising a BET specific surface area of 0.90 m^2/g or more and 2.50 m^2/g or less.

[Claim 4] The silver powder according to any one of claims 1 to 3, for use in a resin-curable conductive paste.

[Claim 5] A resin-curable conductive paste comprising the silver powder according to any one of claims 1 to 3.